RoHS

COMPLIANT

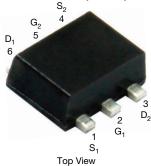
HALOGEN FREE



Complementary N- and P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY							
	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (TYP.)			
	20	0.396 at $V_{GS} = 4.5 \text{ V}$	0.50				
N-Channel		0.456 at V _{GS} = 2.5 V	0.20	0.75 nC			
		0.546 at V _{GS} = 1.8 V	0.20	0.75110			
		0.760 at V _{GS} = 1.5 V	0.05				
P-Channel	-20	0.756 at $V_{GS} = -4.5 \text{ V}$	-0.35				
		1.038 at V _{GS} = -2.5 V	-0.35	1 nC			
		1.440 at V _{GS} = -1.8 V	-0.10	1110			
		2.400 at V _{GS} = -1.5 V	-0.05				

SC-89 Dual (6 leads)



Marking Code: 5
Ordering Information:

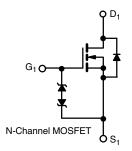
Si1016CX-T1-GE3 (Lead (Pb)-free and Halogen-free)

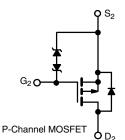
FEATURES

- TrenchFET® power MOSFETs
- · High-side switching
- · Ease in driving switches
- · Low offset (error) voltage
- Low-voltage operation
- · High-speed circuits
- Typical ESD protection: n-channel 900 V, p-channel 900 V (HBM)
- 100 % R_g tested
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Load switch, small signal switches and level-shift switches
 - Battery operated systems
 - Portable





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT				
Drain-Source Voltage		V _{DS}	20	-20	V			
Gate-Source Voltage	V_{GS}	±	V					
Continuous Dunin Comment /T 150 °C)	T _A = 25 °C	- I _D -	0.6 ^{a, b}	-0.6 ^{a, b}				
Continuous Drain Current (T _J = 150 °C)	T _A = 70 °C		0.49 ^{a, b}	-0.49 ^{a, b}	Α			
Pulsed Drain Current (t = 300 μs)	I _{DM}	2	-1.5	A				
Source Drain Current Diode Current T _A = 25 °C		I _S	0.18 ^{a, b}	-0.18 ^{a, b}				
Maximum Power Dissipation	T _A = 25 °C	Р	0.22 ^{a, b}	0.22 ^{a, b}	W			
Maximum Fower Dissipation	T _A = 70 °C	P _D	0.14 ^{a, b}	0.14 ^{a, b}	VV			
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150		°C				

THERMAL RESISTANCE RATINGS								
PARAMETER	SYMBOL	N-CHANNEL		P-CHANNEL		UNIT		
PARAMETER		TYP.	MAX.	TYP.	MAX.	ONII		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 5 s	R _{thJA}	470	565	470	565	°C/W	
Maximum Junction-to-Ambient 4,7	Steady State		560	675	560	675	C/VV	

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 675 °C/W.



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PARAMETER	SYMBOL	rwise noted) TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static					1	l		
		V _{GS} = 0 V, I _D = 250 μA	N-Ch	20	-	_		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	P-Ch	-20	-	_	V	
		I _D = 250 μA	N-Ch	-	17	-	 	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = -250 μA	P-Ch	-	-12	-	mV/°C	
V T	7	I _D = 250 μA	N-Ch	-	-1.8	-		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	P-Ch	-	1.8	-		
Cata Thursels and Valtages		$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	0.4	-	1	V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	P-Ch	-0.4	-	-1	V	
		V - 0 V V - + 4 5 V	N-Ch	-	-	± 1		
Cata Sauraa Laakaga		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	P-Ch	-	-	± 1		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	N-Ch	-	-	± 30		
		$v_{DS} = o v, v_{GS} = \pm o v$	P-Ch	-	-	± 30	1 .	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch	-	-	1	- μΑ	
Zero Gate Voltage Drain Current	le e e	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch	-	-	-1		
Zero Gate Voltage Drain Guirent	I _{DSS}	V_{DS} = 20 V, V_{GS} = 0 V, T_J = 55 °C	N-Ch	-	-	10		
		V_{DS} = -20 V, V_{GS} = 0 V, T_J = 55 °C	P-Ch	ı	-	-10		
On-State Drain Current ^b	In co	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	2	-	-	А	
	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	-1.5	-	-		
		$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$	N-Ch	-	0.330	0.396	Ω	
		$V_{GS} = -4.5 \text{ V}, I_D = -0.35 \text{ A}$	P-Ch	-	0.630	0.756		
	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 0.2 \text{ A}$	N-Ch	-	0.380	0.456		
Drain-Source On-State Resistance b		$V_{GS} = -2.5 \text{ V}, I_D = -0.35 \text{ A}$	P-Ch	-	0.865	1.038		
Drain-Source On-State Resistance		$V_{GS} = 1.8 \text{ V}, I_D = 0.2 \text{ A}$	N-Ch	-	0.420	0.546		
		$V_{GS} = -1.8 \text{ V}, I_D = -0.1 \text{ A}$	P-Ch	-	1.200	1.440		
		$V_{GS} = 1.5 \text{ V}, I_D = 0.05 \text{ A}$	N-Ch	-	0.505	0.760		
		$V_{GS} = -1.5 \text{ V}, I_D = -0.05 \text{ A}$	P-Ch	-	1.600	2.400		
Forward Transconductance b	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.5 \text{ A}$	N-Ch	-	2	-	s	
Torward Transconductanes	91s	$V_{DS} = -10 \text{ V}, I_D = -3.6 \text{ A}$	P-Ch	-	1	-	5	
Input Capacitance	C _{iss}		N-Ch	-	43	-	- pF	
put cupuonaco	0155	N-Channel	P-Ch	-	45	-		
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch	-	14	-		
	- 033	P-Channel	P-Ch	-	15	-		
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch	-	8	-		
·			P-Ch	-	10	-		
Dynamic ^a	_					1	1	
		$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{ A}$	N-Ch	-	1.3	2		
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -0.4 \text{ A}$	P-Ch	-	1.65	2.50		
-	9		N-Ch	-	0.75	1.2		
	Q _{gs}	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$	P-Ch	-	1	2	nC	
Gate-Source Charge		v _{DS} - 10 v, v _{GS} = 2.3 v, I _D = 0.0 A	N-Ch	-	0.15	-		
		P-Channel	P-Ch	-	0.2	-		
Gate-Drain Charge	Q_{gd}	$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_D = -0.4 \text{ A}$	N-Ch	-	0.13	-		
	gu		P-Ch	-	0.26			
Gate Resistance	R_g	f = 1 MHz	N-Ch	2.4	12.2	24.4	Ω	
	Πg		P-Ch	2.4	12	24] 12	



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PARAMETER	SYMBOL	L TEST CONDITIONS			TYP.	MAX.	UNIT	
Dynamic ^a						•		
Turn-On Delay Time	t _{d(on)}		N-Ch	-	11	20		
Turn on Bolay Time	-d(on)	N-Channel	P-Ch	-	9	18		
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 20 \Omega$		-	16	24		
	'	$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	P-Ch	-	10	20		
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch	-	26	39		
	- (- ,	V_{DD} = -10 V, R_L = 33.3 Ω $I_D \cong$ -0.3 A, V_{GEN} = -4.5 V, R_α = 1 Ω	P-Ch	-	10	20	.	
Fall Time	t _f	.b =, .dLN,g	N-Ch P-Ch	-	11 8	20 16		
			N-Ch		2	4	ns	
Turn-On Delay Time	t _{d(on)}		P-Ch		1	2	-	
	t _r	N-Channel V_{DD} = 10 V, R_L = 20 Ω	N-Ch	-	13	20		
Rise Time		$I_D \cong 0.5 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$	P-Ch	-	8	16		
		P-Channel	N-Ch	-	7	14		
Turn-Off Delay Time	t _{d(off)}	V_{DD} = -10 V, R_L = 33.3 Ω	P-Ch	-	9	18	- - -	
E-U.T.	t _f	$I_D\cong$ -0.3 A, V_{GEN} = -8 V, R_g = 1 Ω	N-Ch	-	5	10		
Fall Time			P-Ch	-	5	10		
Drain-Source Body Diode Characterist	ics							
Pulse Diode Forward Current ^a	I _{SM}		N-Ch	-	-	2	Α	
Tales Block Forward Carrent	, 2IAI		P-Ch	-	-	-1.5		
Body Diode Voltage	V_{SD}	$I_S = 0.5 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch	-	0.85	1.2	V	
	- 30	$I_S = -0.3 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch	-	-0.87	-1.2		
Body Diode Reverse Recovery Time	t _{rr}		N-Ch	-	10	20	ns	
		N-Channel	P-Ch	-	16	24		
Body Diode Reverse Recovery Charge		I _F = 0.5 A, dI/dt = 100 A/μs, T _{.I} = 25 °C	N-Ch	-	2	4	nC	
	1	αι/αι = 100 A/μs, 1 _J = 25 C	P-Ch	-	8	20		
Reverse Recovery Fall Time	ta	P-Channel $I_F = -0.3 A$,	N-Ch	-	5			
		ι _F = -0.3 A, dl/dt = -100 A/μs, T _J = 25 °C	P-Ch	-	11	-	ns	
Reverse Recovery Rise Time	t _b	, , ,	N-Ch	-	5	-		
			P-Ch	-	5	-		

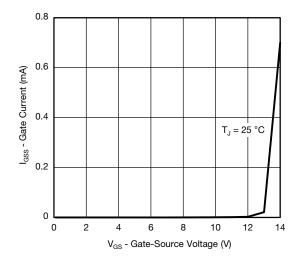
Notes

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

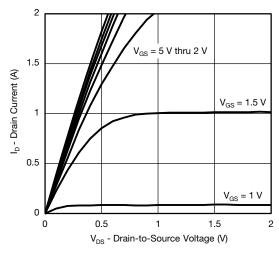
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



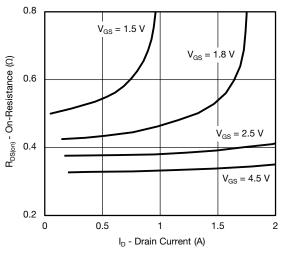
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



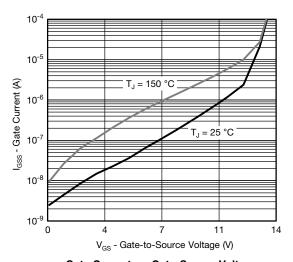
Gate Current vs. Gate-Source Voltage



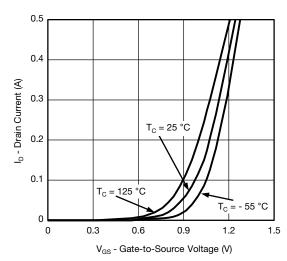
Output Characteristics



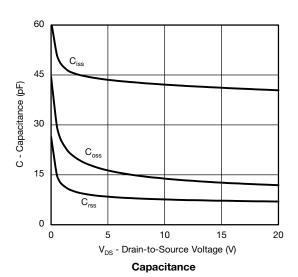
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage

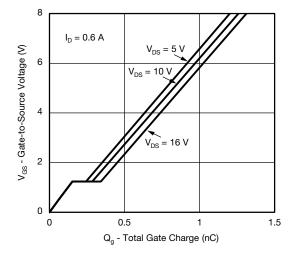


Transfer Characteristics

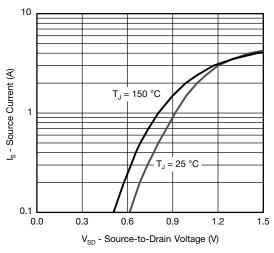




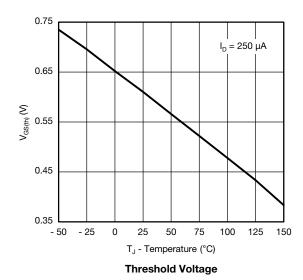
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

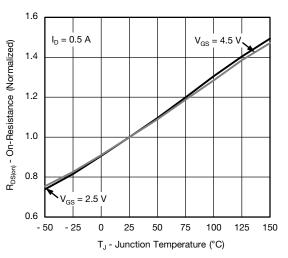


Gate Charge

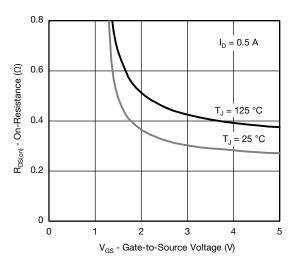


Source-Drain Diode Forward Voltage

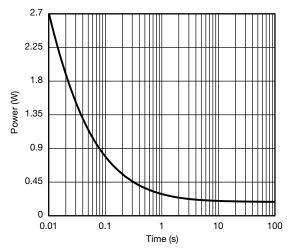




On-Resistance vs. Junction Temperature



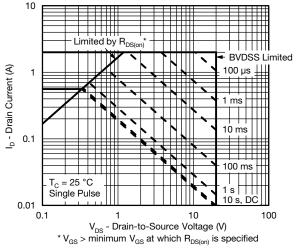
On-Resistance vs. Gate-to-Source Voltage

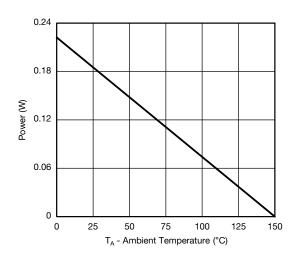


Single Pulse Power, Junction-to-Ambient



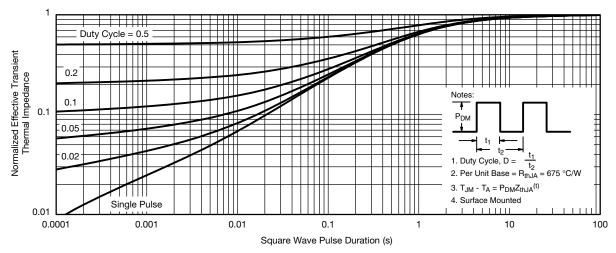
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

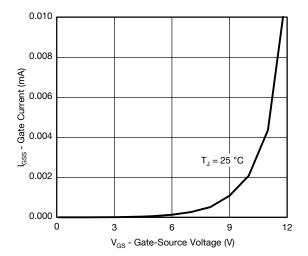
Power Derating, Junction-to-Ambient



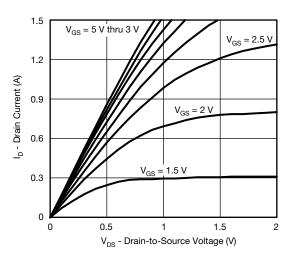
Normalized Thermal Transient Impedance, Junction-to-Ambient



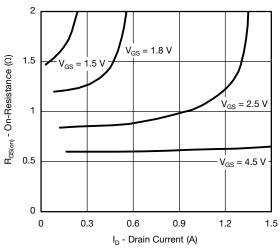
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



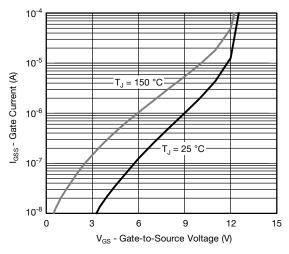
Gate Current vs. Gate-Source Voltage



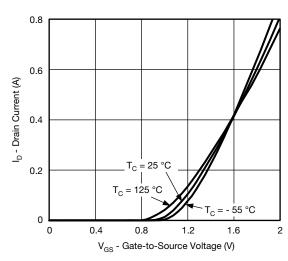
Output Characteristics



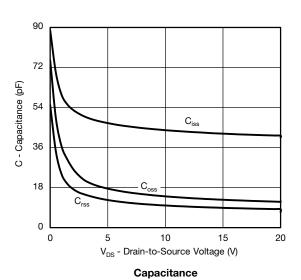
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage

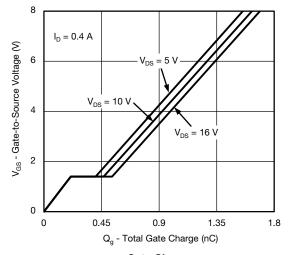


Transfer Characteristics

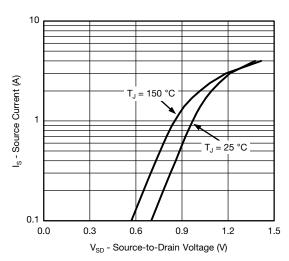




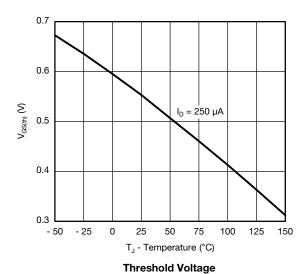
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Gate Charge

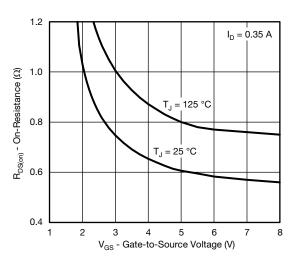


Source-Drain Diode Forward Voltage

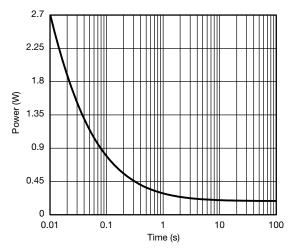


1.5 $I_D = 0.35 A$ $V_{GS} = 2.5 \text{ V}$ R_{DS(on)} - On-Resistance (Normalized) 1.3 $V_{GS} = 4.5 \text{ V}$ 1.1 0.9 0.7 - 25 50 100 125 150 - 50 T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature



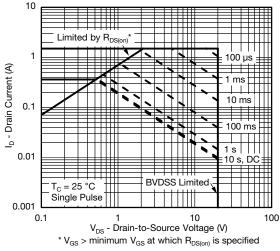
On-Resistance vs. Gate-to-Source Voltage

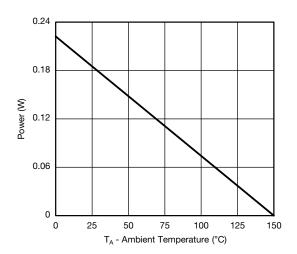


Single Pulse Power, Junction-to-Ambient



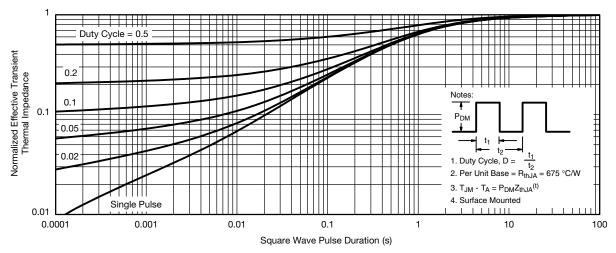
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

Power Derating, Junction-to-Ambient

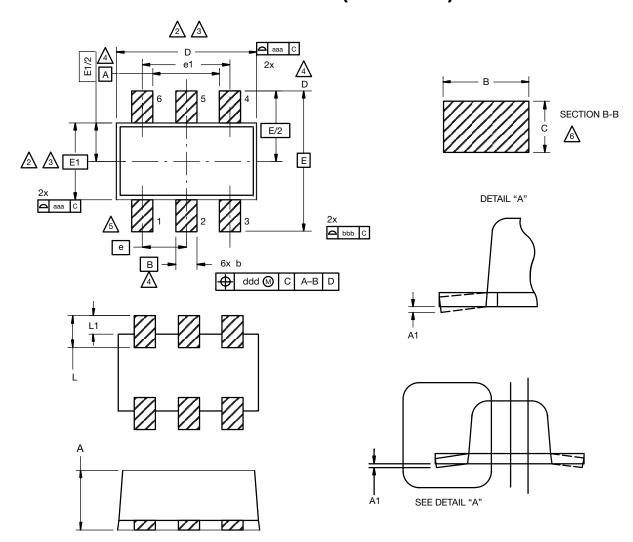


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg267535.



SC-89 6-Leads (SOT-563F)



Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

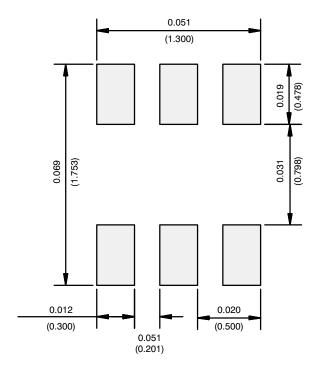
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
DIIVI.	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			
C14-0439-Rev. C, 11-Aug-14 DWG: 5880						



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

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AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























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